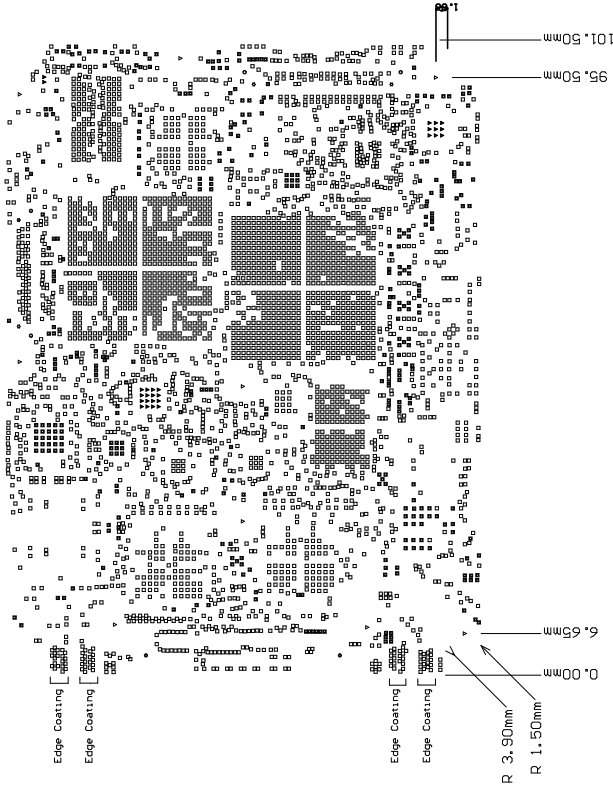


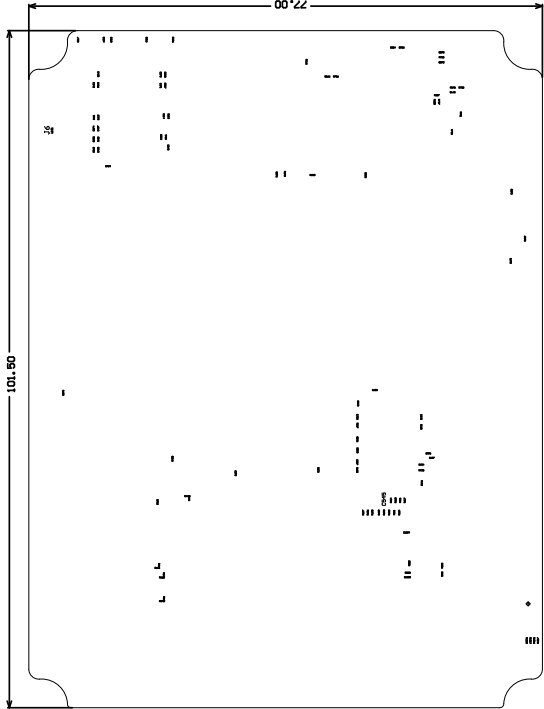
DRILL



- NOTES : UNLESS OTHERWISE SPECIFIED
1. SPEC: IPC-6012 CLASS 3 AND IPC600 CLASS 3.
IN LOCATIONS WHERE DUE TO THE HIGH CIRCUIT DENSITY, WE HAVE REDUCED THE DESIGNED ANNULAR RING TO 5 MILS (0.125 MM), WE ONLY ALLOW TANGENCY OF THE VIAS TO THE PADS. WE DON'T ALLOW BREAKOUT.
 2. NUMBER OF LAYERS : 18
 3. BOARD THICKNESS INCLUDING COPPER COATING : 1.93mm +/-10%
 4. MATERIAL: FR4
 - a) IIEQ IT180A or ISLA 370HR, Tg =>170 Deg C, PER IPC4101/126
 - b) UL-94V-0 UNDERWRITERS LABORATORIES APPROVAL
 5. LAYER STACK-UP: ACCORDING TO PDF FILES (ATTACHED TO ORDER)
 6. COPPER FOIL IN ACCORDANCE WITH IPC-MF-150.
 7. TWIST AND BOW <0.75%
 8. SOLDERMASK BOTH SIDES : ACCORDANCE WITH IPC-SM-840 CLASS-3.
RECOMMENDED TAYO PSR 4000 OR TAMURA DSR2500 OR EQUIV.
SOLDER MASK THICKNESS SOULD BE 15-25 MICRON.
 9. FINISH: ENIG IMMERSION GOLD OVER ELECTROLESS NICKEL PER IPC 4552.
 10. ALL HOLES DIMENSIONS ARE AFTER PLATING.
 11. ALL VIA DRILL SHOULD PASS FILING AND CAPPING PROCESS (ACCORDING TO DRILL TABLE BELOW).
 12. SILKSCREEN : WHITE
 13. The following information shall appear in silk screen:
 - a) UL-94V-0.
 - b) Manufacturer name or trademark.
 - c) Date code ww/yy
 14. The PCB will be completely RoHS compliant as defined by Directive 2011/65/EC of the European Parliament.
 15. EACH PRODUCTION BATCH / LOT SHOULD BE DELIVERED WITH C.O.C. TEST REPORT AND TEST COUPON PER LOT.
 16. Electrical test: continuity and insulation at 250V_100% on all board shall be performed according too the Netlist.
 17. The Gerber files shall be compared to the Netlist.
 18. PACKAGING SHOULD BE ACCORDING TO 1601 A.
 19. ADD TWO MARGINS 5mm WIDTH TO PCB BOARD.

| Symbol | Hole Size | Count | Plated | Via/Pad | Hole Tolerance |
|--------|-----------|------------|--------|---------|-----------------|
| □ | 0.20mm | 3815 | PTH | Uta | +0.05mm/-0.10mm |
| ▣ | 0.25mm | 372 | PTH | Uta | +0.05mm/-0.10mm |
| ▤ | 0.30mm | 27 | PTH | Uta | +0.05mm/-0.10mm |
| ⊕ | 1.00mm | 4 | PTH | pad | +/-0.08mm |
| ⊗ | 1.80mm | 2 | PTH | pad | +/-0.08mm |
| ▽ | 2.30mm | 9 | PTH | pad | +/-0.08mm |
| ⊛ | 1.50mm | 4 | NPTH | pad | +/-0.05mm |
| | | 4233 Total | | | |

| | | | |
|--------------|-----------------|----------|-----------|
| COMPANY: | | COMMTACT | |
| PROJECT: | DIGITAL PHOENIX | DATE: | 14-Feb-24 |
| LAYER : | | | |
| PCB9550227-D | | | |



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